

PSR[®]-4000 HS Series

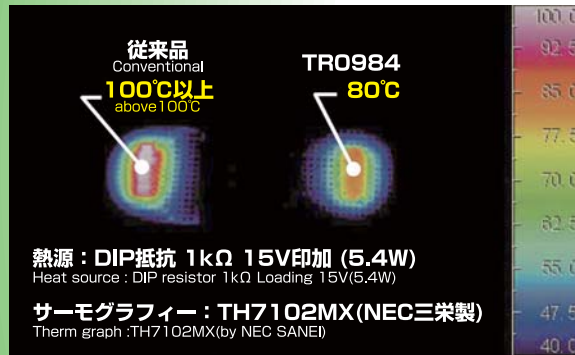
PHOTOFINER[®]

放熱対策現像型ソルダーレジスト

Photoimageable Solder Resist Heat Spreader

特長 Features

- 熱伝導率が従来の現像型ソルダーレジストの約10倍^{※(当社比)}
On Thermal conductivity, it is ten times as high as conventional Photoimageable Solder Resist
- プリント基板の熱拡散が可能
Heat diffusion of PWB can be performed.



仕様・特性 Specifications & properties

Items	PSR [®] -4000HS(TR0984)	PSR [®] -4000G Series	試験条件 Remarks/Test Condition
色調 Color	White	Green	
露光量 Exposure Energy	700mJ/cm ²	400mJ/cm ²	Under Mylar film
現像時間 Development Time	90 sec	60 sec	1wt% Na ₂ CO ₃ @30°C
ポストキュア Post Cure	150°C×60 min	150°C×60 min	
Tg, CTE ($\alpha 1/\alpha 2$)	Tg=145°C 25/55 ppm	Tg=100°C 47/134 ppm	TMA
吸水率 Water absorption	0.5%	1.4%	Room temperature 24hr
はんだ耐熱性 Solder heat resistance	Good	Good	260°C×10sec.×3cycles
無電解金めっき耐性 Ni/Au plating resistance	Good	Good	Ni/3μm Au 0.05μm
解像性 Resolution between QFP pads	80μm	50μm	Thickness 50±3μm
熱伝導率 Thermal conductivity	2.2W/m·K	0.2W/m·K	



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